

## Material Dispensing - Frequently Asked Questions

### Q. What is Recommended Dot Size Universal recommends for a particular component pad layout?

A. The space between the pads dictates the recommended dot diameter of adhesive that should be dispensed between the pads, not the component type. Some boards are designed for implementation of adhesive and some designed for implementation of solder paste. Boards designed for adhesive have a larger pad spacing than boards designed for solder paste deposition. Once the pad spacing is known, a nozzle to suit the customer application is recommended.

### Q. What Material does Universal recommend that the customer use for a particular process?

A. The dispensing material is application dependant. Adhesives such as Loctite, Amicon, Hereaus, and Epibond have all been qualified to run on Universal's dispensing machine. Other materials like solder pastes, silver filled epoxies and flux encapsulates have also been required to run Universal's dispensing machine.

### Q. Can I dispense adhesive between component pads that have Solder Paste on them?

A. Yes, however special nozzles are required that prevent nozzle contamination in the solder paste. All nozzles incorporate a stand-off or post of some sort to maintain the height of the dispensing surgical tube from the PC board. This post or standoff must contact the board, therefore it is critical to position this where it won't get contaminated by the previously placed solder paste.

### Q. How does the customer eliminate Stringing, Tailing, and other Material Process Related Issues?

A. Material Process Related Issues are typically attributed to improper machine set up parameters. Therefore confirmation that the machine is properly set-up along with verification that all machine parameters on the GDM have been completed, is the first approach in attempting to resolve these issues. White papers and technical articles, along with videos and training manuals that have been written, are available to assist the customer resolving this issue.

### Q. What Nozzle Tooling does Universal recommend for a particular process?

A. The board design and manufacturing process usually dictate which nozzle will be most suitable for a particular application. Universal offers an on line nozzle catalogue that provides detailed drawings and dimensions of hundreds of different nozzles.

### Q. When does Universal recommend utilization of Dual Dots? Single Dots?

A. It is recommended that dual dots be used as often as possible as it provides a twice the amount of holding power than a single dot of the same size. On boards that have been manufactured with pad spacing for depositional of adhesive, dual dots are recommended for components sizes down to 0805 in size.

### Q. Does Universal have any articles or white papers on dispensing adhesive? Solder Paste? Process?

A. Technical articles and white papers, along with videos and training manuals are available upon request. We also have quite a bit of [[information online](/wcms/WCMS.nsf/index/Material_Dispensing_14.html)].

### Q. Can the customer dispense Solder Paste, Silver Filled Epoxy, other materials? How?

A. The dispensing material is application dependant. Adhesives such as Loctite, Amicon, Hereaus, and Epibond have all been qualified to run on Universal's dispensing machine. Other materials like solder pastes, silver filled epoxies and flux encapsulates have also been required to run Universal's dispensing machine.

### Q. What can you tell me about machine set up?

A. [[White papers and technical articles](/wcms/WCMS.nsf/index/Material_Dispensing_14.html)] along with videos, training manuals and 24 hour technical support are available to assist the customer in resolving set up issues.

### Q. Can you help me with part number identification?

A. Technical support is available 24 hours a day to assist the customer in resolving part number issues. Most information can also be found in the Material Deposition And Spare Parts Guide.